

# ABSTRACT

5 A chip size package in which an elastomer of low  
elasticity for damping and absorbing a stress, as  
might otherwise be concentrated on bump electrodes, is  
10 formed over the principal face of a semiconductor chip  
and in which wires connected with bonding pads are led  
out to the upper face of the elastomer through through  
holes formed in the elastomer and are connected at  
their one-end portions with the bump electrodes. On  
15 the other hand, the wires, as led out to the upper  
face of the elastomer are formed in a curved pattern  
so that the stress to be concentrated on the bump  
electrodes may be absorbed and damped by the extension  
and contraction of not only the elastomer but also the  
wires.